

September 2007

# FSQ0365, FSQ0265, FSQ0165, FSQ321, FSQ311 Green Mode Fairchild Power Switch (FPS™) for Valley Switching Converter - Low EMI and High Efficiency

#### **Features**

- Optimized for Valley Switching (VSC)
- Low EMI through Variable Frequency Control and Inherent Frequency Modulation
- High-Efficiency through Minimum Voltage Switching
- Narrow Frequency Variation Range over Wide Load and Input Voltage Variation
- Advanced Burst-Mode Operation for Low Standby Power Consumption
- Pulse-by-Pulse Current Limit
- Various Protection Functions: Overload Protection (OLP), Over-Voltage Protection (OVP), Abnormal Over-Current Protection (AOCP), Internal Thermal Shutdown (TSD)
- Under-Voltage Lockout (UVLO) with Hysteresis
- Internal Start-up Circuit
- Internal High-Voltage SenseFET (650V)
- Built-in Soft-Start (15ms)

### **Applications**

- Power Supply for DVP Player and DVD Recorder, Set-Top Box
- Adapter
- Auxiliary Power Supply for PC, LCD TV, and PDP TV

### **Related Application Notes**

- AN-4137, AN-4141, AN-4147, AN-4150 (Flyback)
- AN-4134 (Forward)

#### Description

A Valley Switching Converter generally shows lower EMI and higher power conversion efficiency than a conventional hard-switched converter with a fixed switching frequency. The FSQ-series is an integrated Pulse-Width Modulation (PWM) controller and SenseFET specifically designed for valley switching operation with minimal external components. The PWM controller includes an integrated fixed-frequency oscillator, Under-Voltage Lockout, Leading Edge Blanking (LEB), optimized gate driver, internal soft-start, temperature-compensated precise current sources for loop compensation, and self-protection circuitry.

Compared with discrete MOSFET and PWM controller solutions, the FSQ-series reduces total cost, component count, size and weight; while simultaneously increasing efficiency, productivity, and system reliability. This device provides a basic platform that is well suited for cost-effective designs of valley switching fly-back converters.

FPS™ is a trademark of Fairchild Semiconductor Corporation.

### **Ordering Information**

		_	Cur-		Maximum Output Power <sup>(1)</sup>				
Product Number <sup>(5)</sup>	PKG.	Operating Temp.	rent	t R <sub>DS(ON)</sub>	230VAC±15% <sup>(2)</sup>		85-265VAC		Replaces Devices
		·	Limit		Adapter <sup>(3)</sup>	Open-Frame <sup>(4)</sup>	Adapter <sup>(3)</sup>	Open-Frame <sup>(4)</sup>	
FSQ311	8-DIP	-40 to +85C	0.6A	19Ω	7W	10W	6W	8W	FSDL321
FSQ311L	8-LSOP	-40 10 1000	0.0A	1022	/ VV	1000	OVV	OVV	FSDM311
FSQ321	8-DIP	-40 to +85°C	0.6A	19Ω	8W	12W	7W	10W	FSDL321
FSQ321L	8-LSOP	-40 10 103 0	0.04	1032	011	1244	7 **	1011	FSDM311
FSQ0165RN	8-DIP	-40 to +85°C	0.9A	10Ω	10W	15W	9W	13W	FSDL0165RN
FSQ0165RL	8-LSOP	-40 10 103 0	0.5/4	1022	1000	1000	300	1300	1 SDE010SIKIN
FSQ0265RN	8-DIP	-40 to +85°C	1 2 1	6Ω	14W	20W	11W	16W	FSDM0265RN
FSQ0265RL	8-LSOP	-40 to +65 C	1.2A	075	1400	2000	1100	70 1000	FSDM0265RNB
FSQ0365RN	8-DIP	-40 to +85°C	1.5A	4.5Ω	17.5W	25W	13W	19W	FSDM0365RN
FSQ0365RL	8-LSOP	- <del>4</del> 0 to +65 C	1.5A	4.512	17.500	2300	1300	1900	FSDM0365RNB

#### Notes:

- 1. The junction temperature can limit the maximum output power.
- 2.  $230V_{AC}$  or  $100/115V_{AC}$  with doubler. The maximum power with CCM operation.
- 3. Typical continuous power in a non-ventilated enclosed adapter measured at 50°C ambient temperature.
- 4. Maximum practical continuous power in an open-frame design at 50°C ambient.
- 5. Pb-free package per JEDEC J-STD-020B.

### **Typical Circuit**

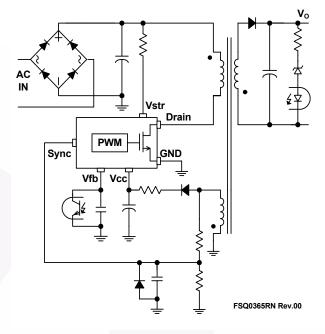


Figure 1. Typical Flyback Application

### **Internal Block Diagram**

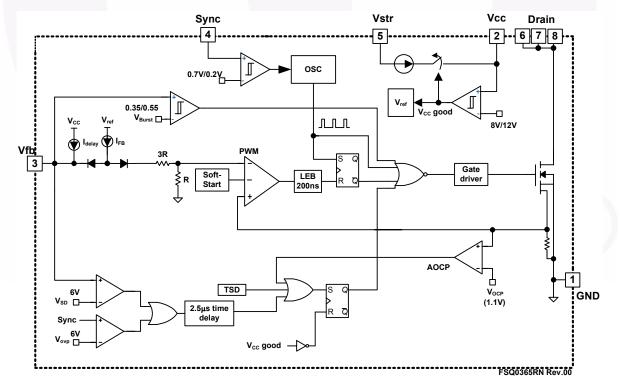


Figure 2. Functional Block Diagram

## **Pin Configuration**

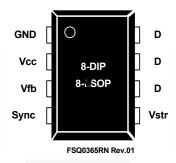


Figure 3. Pin Configuration (Top View)

### **Pin Definitions**

Pin#	Name	Description
1	GND	SenseFET source terminal on primary side and internal control ground.
2	Vcc	Positive supply voltage input. Although connected to an auxiliary transformer winding, current is supplied from pin 5 (Vstr) via an internal switch during startup (see Internal Block Diagram Section). It is not until $V_{CC}$ reaches the UVLO upper threshold (12V) that the internal start-up switch opens and device power is supplied via the auxiliary transformer winding.
3	Vfb	The feedback voltage pin is the non-inverting input to the PWM comparator. It has a 0.9mA current source connected internally while a capacitor and optocoupler are typically connected externally. There is a time delay while charging external capacitor Cfb from 3V to 6V using an internal $5\mu A$ current source. This time delay prevents false triggering under transient conditions but still allows the protection mechanism to operate under true overload conditions.
4	Sync	This pin is internally connected to the sync-detect comparator for valley switching. Typically the voltage of the auxiliary winding is used as Sync input voltage and external resistors and capacitor are needed to make time delay to match valley point. The threshold of the internal sync comparator is 0.7V/0.2V.
5	Vstr	This pin is connected to the rectified AC line voltage source. At start-up the internal switch supplies internal bias and charges an external storage capacitor placed between the Vcc pin and ground. Once the Vcc reaches 12V, the internal switch is opened.
6,7,8	Drain	The drain pins are designed to connect directly to the primary lead of the transformer and are capable of switching a maximum of 700V. Minimizing the length of the trace connecting these pins to the transformer will decrease leakage inductance.

### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A = 25^{\circ}C$ , unless otherwise specified.

Symbol	Characteristic	Min.	Max.	Unit		
V <sub>STR</sub>	V <sub>str</sub> Pin Voltage		500		V	
V <sub>DS</sub>	Drain Pin Voltage		650		V	
V <sub>CC</sub>	Supply Voltage			20	V	
V <sub>FB</sub>	Feedback Voltage Range		-0.3	9.0	V	
V <sub>Sync</sub>	Sync Pin Voltage Range		-0.3	9.0	V	
		FSQ0365		12		
	Drain Current Pulsed <sup>(6)</sup>	FSQ0265		8		
I <sub>DM</sub>	Diam Current Fulsed.	FSQ0165		4	Α	
		FSQ321/311		1.5		
		FSQ0365		230		
_	Single Pulsed Avalanche Energy <sup>(7)</sup>	FSQ0265		140	mJ	
E <sub>AS</sub>		FSQ0165		50	IIIJ	
		FSQ321/311		10		
$P_{D}$	Total Power Dissipation			1.5	W	
TJ	Recommended Operating Junction T	-40	Internally limited	°C		
T <sub>A</sub>	Operating Ambient Temperature	-40	85	°C		
T <sub>STG</sub>	Storage Temperature	-55	150	°C		
ESD	Human Body Model <sup>(8)</sup>	CLASS1 C				
ESD	Machine Model <sup>(8)</sup>		CLASS B			

#### Notes:

- 6. Repetitive rating: Pulse width limited by maximum junction temperature.
- 7. L=51mH, starting T<sub>J</sub>=25°C.
- 8. Meets JEDEC standards JESD22-A114 and JESD22-A115.

### Thermal Impedance

Symbol	Parameter	Value	Unit		
8-DIP <sup>(9)</sup>					
$\theta_{JA}^{(10)}$	Junction-to-Ambient Thermal Resistance	80			
θ <sub>JC</sub> <sup>(11)</sup>	Junction-to-Case Thermal Resistance 20				
$\theta_{\rm JT}^{(12)}$	Junction-to-Top Thermal Resistance	35			

#### Notes:

- 9. All items are tested with the standards JESD 51-2 and 51-10 (DIP).
- 10. Free-standing, with no heat-sink, under natural convection.
- 11. Infinite cooling condition refer to the SEMI G30-88.
- 12. Measured on the package top surface.

### **Electrical Characteristics**

 $T_A = 25$ °C unless otherwise specified.

Symbol	Paramete	r	Condition	Min.	Тур.	Max.	Unit	
SenseFET	Section			I.		· L		
BV <sub>DSS</sub>	Drain Source Breakdow	n Voltage	V <sub>CC</sub> = 0V, I <sub>D</sub> = 100μA	650			V	
I <sub>DSS</sub>	Zero-Gate-Voltage Drain	n Current	V <sub>DS</sub> = 560V			100	μA	
		FSQ0365			3.5	4.5		
D	Drain-Source On-State	FSQ0265	T = 25°C   = 0.5A		5.0	6.0	_	
R <sub>DS(ON)</sub>	Resistance <sup>(13)</sup>	FSQ0165	$T_J = 25^{\circ}C, I_D = 0.5A$		8.0	10.0	Ω	
		FSQ321/311			14.0	19.0		
		FSQ0365			315			
C	Input Canacitance	FSQ0265	\		550		nE	
C <sub>SS</sub>	Input Capacitance	FSQ0165	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		250		pF	
		FSQ321/311			162			
		FSQ0365			47			
0	Outrot Conneitones	FSQ0265	\		38			
C <sub>OSS</sub>	Output Capacitance	FSQ0165	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		25		pF	
		FSQ321/311			18			
		FSQ0365			9.0		pF	
0	Reverse Transfer Capacitance	FSQ0265	3,4 3,4 3,5,4 4,4,4		17.0			
C <sub>RSS</sub>		FSQ0165	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		10.0			
		FSQ321/311			3.8			
		FSQ0365			11.2		ns	
	T . O D I T	FSQ0265	)		20.0			
t <sub>d(on)</sub>	Turn-On Delay Time	FSQ0165	$V_{DD} = 350V, I_{D} = 25mA$		12.0			
		FSQ321/311			9.5			
		FSQ0365			34		ns	
	Discourse Trans	FSQ0265	V <sub>DD</sub> = 350V, I <sub>D</sub> = 25mA		15			
t <sub>r</sub>	Rise Time	FSQ0165			4			
		FSQ321/311			19			
		FSQ0365			28.2			
	T O(( D T)	FSQ0265	1, 250, 1, 25, 4		55.0			
t <sub>d(off)</sub>	Turn-Off Delay Time	FSQ0165	$V_{DD} = 350V, I_{D} = 25mA$		30.0		ns	
		FSQ321/311			33.0			
		FSQ0365			32			
	Fall Times	FSQ0265	), 050V, 1 05A		25			
t <sub>f</sub>	Fall Time	FSQ0165	$V_{DD} = 350V, I_{D} = 25mA$		10	VI.	ns	
		FSQ321/311			42			
Control Se	ection				•			
t <sub>ON.MAX1</sub>	Maximum On Time1	All but Q321	T <sub>J</sub> = 25°C	10.5	12.0	13.5	μs	
t <sub>ON.MAX2</sub>	Maximum On Time2	Q321	T <sub>J</sub> = 25°C	6.35	7.06	7.77	μs	
t <sub>B1</sub>	Blanking Time1	All but Q321		13.2	15.0	16.8	μs	
t <sub>B2</sub>	Blanking Time2	Q321		7.5	8.2		μs	
	l .				1			

### **Electrical Characteristics** (Continued)

 $T_A = 25$ °C unless otherwise specified.

Symbol	Parameter		Condition	Min.	Тур.	Max.	Unit	
t <sub>W</sub>	Detection Time Window		$T_J = 25^{\circ}C$ , $V_{sync} = 0V$		3.0		μs	
f <sub>S1</sub>	Initial Switching Freq.1	All but Q321		50.5	55.6	61.7	kHz	
f <sub>S2</sub>	Initial Switching Freq.2	Q321		84.0	89.3	95.2	kHz	
Δf <sub>S</sub>	Switching Frequency Varia	ition <sup>(14)</sup>	-25°C < T <sub>J</sub> < 85°C		±5	±10	%	
I <sub>FB</sub>	Feedback Source Current		V <sub>FB</sub> = 0V	700	900	1100	μΑ	
D <sub>MIN</sub>	Minimum Duty Cycle		V <sub>FB</sub> = 0V			0	%	
V <sub>START</sub>	UVLO Threshold Voltage		After turn-on	11	12	13	V	
V <sub>STOP</sub>	OVLO Tillesilola voltage		Alter turn-on	7	8	9	V	
t <sub>S/S1</sub>	Internal Soft-Start Time1	All but Q321	With free-running frequency		15		ms	
t <sub>S/S2</sub>	Internal Soft-Start Time2	Q321	With free-running frequency		10		ms	
Burst Mod	le Section			•				
V <sub>BURH</sub>				0.45	0.55	0.65	V	
V <sub>BURL</sub>	Burst-Mode Voltage		$T_J = 25^{\circ}C, t_{PD} = 200 \text{ns}^{(15)}$	0.25	0.35	0.45	V	
V <sub>BUR(HYS)</sub>					200		mV	
Protection	Section							
		FSQ0365	$T_J = 25^{\circ}C$ , di/dt = 240mA/ $\mu$ s	1.32	1.50	1.68		
I <sub>LIM</sub>	FSQ026		$T_J = 25^{\circ}C$ , di/dt = 200mA/ $\mu$ s	1.06	1.20	1.34		
	Peak Current Limit	FSQ0165	$T_J = 25^{\circ}C$ , di/dt = 175mA/ $\mu$ s	0.8	0.9	1.0	Α	
	FSQ321		$T_J = 25^{\circ}C$ , di/dt = 125mA/ $\mu$ s	0.53	0.60	0.67		
		FSQ311	$T_J = 25^{\circ}C$ , di/dt = 112mA/ $\mu$ s	0.53	0.60	0.67		
$V_{SD}$	Shutdown Feedback Volta	ge	V <sub>CC</sub> = 15V	5.5	6.0	6.5	V	
I <sub>DELAY</sub>	Shutdown Delay Current		V <sub>FB</sub> = 5V	4	5	6	μΑ	
t <sub>LEB</sub>	Leading-Edge Blanking Tir	ne <sup>(14)</sup>			200		ns	
V <sub>OVP</sub>	Over-Voltage Protection		V <sub>CC</sub> = 15V, V <sub>FB</sub> = 2V	5.5	6.0	6.5	V	
t <sub>OVP</sub>	Over-Voltage Protection Bl	anking Time		2	3	4	μs	
T <sub>SD</sub>	Thermal Shutdown Tempe	rature <sup>(14)</sup>		125	140	155	°C	
Sync Sect	ion			1				
V <sub>SH</sub>	O Thurship and Malks are			0.55	0.70	0.85	V	
V <sub>SL</sub>	Sync Threshold Voltage			0.14	0.20	0.26	V	
t <sub>Sync</sub>	Sync Delay Time <sup>(14)(16)</sup>				300		ns	
	ce Section			1				
I <sub>OP</sub>	Oper. Supply Current (Cor	trol Part Only)	V <sub>CC</sub> = 15V	1	3	5	mA	
I <sub>START</sub>	Start Current		$V_{CC} = V_{START} - 0.1V$ (before $V_{CC}$ reaches $V_{START}$ )	270	360	450	μA	
I <sub>CH</sub>	Start-up Charging Current		V <sub>CC</sub> = 0V, V <sub>STR</sub> = min. 40V	0.65	0.85	1.00	mA	
V <sub>STR</sub>	Minimum V <sub>STR</sub> Supply Voltage			<b>†</b>	26		V	

#### Notes

- 13. Pulse test: Pulse-Width=300μs, duty=2%
- 14. Though guaranteed, it is not 100% tested in production.
- 15. Propagation delay in the control IC.
- 16. Includes gate turn-on time.

### Comparison Between FSDM0x65RNB and FSQ-Series

Function	FSDM0x65RNB	FSQ-Series	FSQ-Series Advantages
Operation method	Constant frequency PWM	Valley switching operation	<ul><li>Improved efficiency by valley switching</li><li>Reduced EMI noise</li></ul>
EMI reduction	Frequency modulation	Valley switching & inherent frequency modulation	■ Reduce EMI noise by two ways
			■ Improved standby power by valley switching also in burst-mode
Burst-mode operation	Fixed burst peak	Advanced burst-mode	Because the current peak during burst operation is dependent on V <sub>FB</sub> , it is easier to solve audible noise
Protection		AOCP	<ul> <li>Improved reliability through precise abnormal over-current protection</li> </ul>

### **Typical Performance Characteristics**

These characteristic graphs are normalized at  $T_A$ = 25°C.

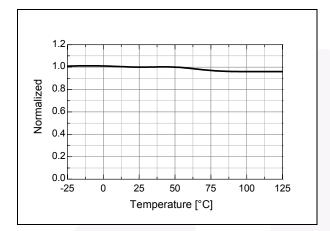


Figure 4. Operating Supply Current (I<sub>OP</sub>) vs. T<sub>A</sub>

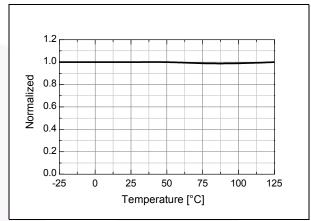


Figure 5. UVLO Start Threshold Voltage (V<sub>START</sub>) vs. T<sub>A</sub>

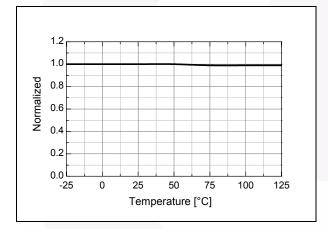


Figure 6. UVLO Stop Threshold Voltage ( $V_{STOP}$ ) vs.  $T_A$ 

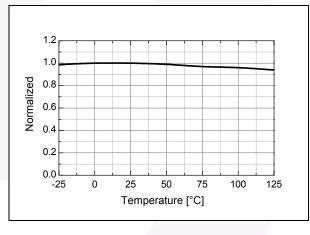


Figure 7. Start-up Charging Current (I<sub>CH</sub>) vs. T<sub>A</sub>

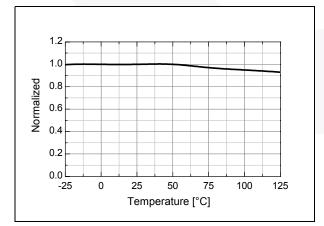


Figure 8. Initial Switching Frequency ( $f_S$ ) vs.  $T_A$ 

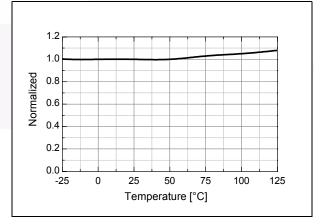
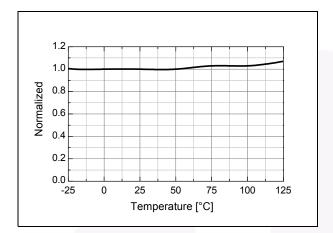


Figure 9. Maximum On Time  $(t_{ON.MAX})$  vs.  $T_A$ 

### **Typical Performance Characteristics** (Continued)

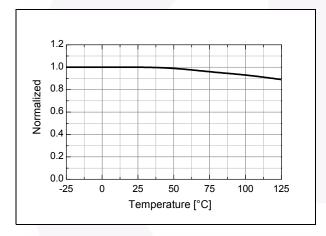
These characteristic graphs are normalized at  $T_A$ = 25°C.



1.2 1.0 0.8 0.6 0.4 0.2 0.0 -25 0 25 50 75 100 125 Temperature [°C]

Figure 10. Blanking Time (t<sub>B</sub>) vs. T<sub>A</sub>

Figure 11. Feedback Source Current (IFB) vs. TA



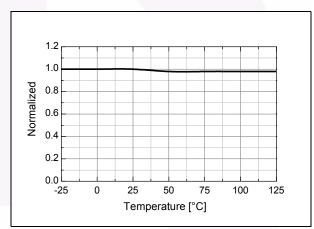
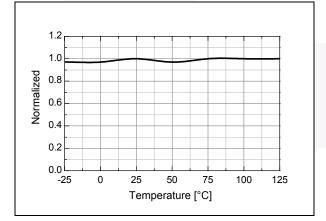


Figure 12. Shutdown Delay Current (I<sub>DELAY</sub>) vs. T<sub>A</sub>

Figure 13. Burst-Mode High Threshold Voltage  $(V_{burh})$  vs.  $T_A$ 



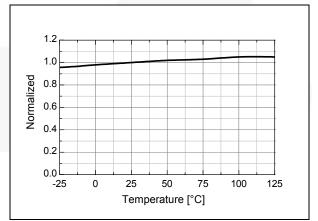
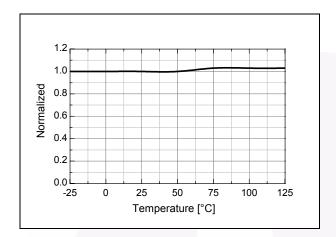


Figure 14. Burst-Mode Low Threshold Voltage  $(V_{burl})$  vs.  $T_A$ 

Figure 15. Peak Current Limit (I<sub>LIM</sub>) vs. T<sub>A</sub>

### **Typical Performance Characteristics** (Continued)

These characteristic graphs are normalized at  $T_A$ = 25°C.



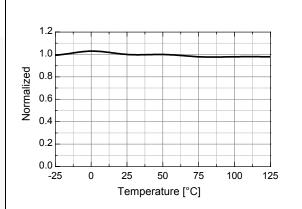
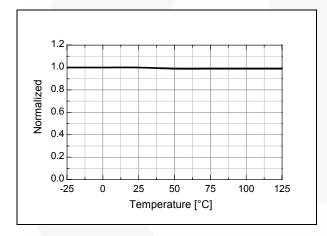


Figure 16. Sync High Threshold Voltage (V<sub>SH</sub>) vs. T<sub>A</sub>

Figure 17. Sync Low Threshold Voltage (V<sub>SL</sub>) vs. T<sub>A</sub>



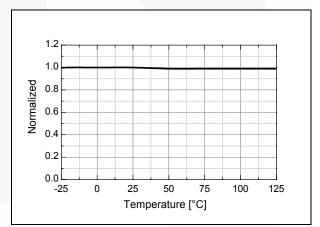


Figure 18. Shutdown Feedback Voltage (V<sub>SD</sub>) vs. T<sub>A</sub>

Figure 19. Over-Voltage Protection (V<sub>OP</sub>) vs. T<sub>A</sub>

### **Functional Description**

1. Startup: At startup, an internal high-voltage current source supplies the internal bias and charges the external capacitor ( $C_a$ ) connected to the Vcc pin, as illustrated in Figure 20. When  $V_{CC}$  reaches 12V, the FPS begins switching and the internal high-voltage current source is disabled. The FPS continues its normal switching operation and the power is supplied from the auxiliary transformer winding unless  $V_{CC}$  goes below the stop voltage of 8V.

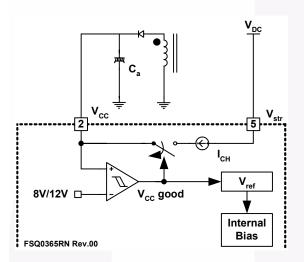


Figure 20. Start-up Circuit

- 2. Feedback Control: FPS employs current mode control, as shown in Figure 21. An opto-coupler (such as the FOD817A) and shunt regulator (such as the KA431) are typically used to implement the feedback network. Comparing the feedback voltage with the voltage across the R<sub>SENSE</sub> resistor makes it possible to control the switching duty cycle. When the reference pin voltage of the shunt regulator exceeds the internal reference voltage of 2.5V, the opto-coupler LED current increases, thus pulling down the feedback voltage and reducing the duty cycle. This event typically happens when the input voltage is increased or the output load is decreased.
- **2.1 Pulse-by-Pulse Current Limit:** Because current mode control is employed, the peak current through the SenseFET is limited by the inverting input of PWM comparator ( $V_{FB}^*$ ), as shown in Figure 21. Assuming that the 0.9mA current source flows only through the internal resistor (3R + R = 2.8k), the cathode voltage of diode D2 is about 2.5V. Since D1 is blocked when the feedback voltage ( $V_{FB}$ ) exceeds 2.5V, the maximum voltage of the cathode of D2 is clamped at this voltage, thus clamping  $V_{FB}^*$ . Therefore, the peak value of the current through the SenseFET is limited.

**2.2 Leading Edge Blanking (LEB):** At the instant the internal SenseFET is turned on, a high-current spike usually occurs through the SenseFET, caused by primary-side capacitance and secondary-side rectifier reverse recovery. Excessive voltage across the  $R_{\text{Sense}}$  resistor would lead to incorrect feedback operation in the current mode PWM control. To counter this effect, the FPS employs a leading edge blanking (LEB) circuit. This circuit inhibits the PWM comparator for a short time ( $t_{\text{LEB}}$ ) after the SenseFET is turned on.

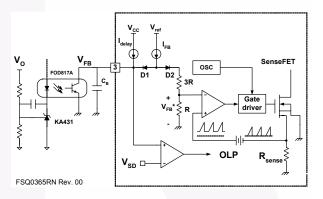


Figure 21. Pulse-Width-Modulation (PWM) Circuit

**3. Synchronization:** The FSQ-series employs a valley switching technique to minimize the switching noise and loss. The basic waveforms of the valley switching converter are shown in Figure 22. To minimize the MOSFET's switching loss, the MOSFET should be turned on when the drain voltage reaches its minimum value, as shown in Figure 22. The minimum drain voltage is indirectly detected by monitoring the  $V_{CC}$  winding voltage, as shown in Figure 22.

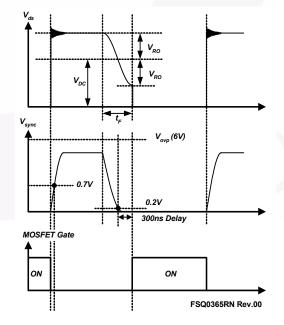


Figure 22. Valley Resonant Switching Waveforms

4. Protection Circuits: The FSQ-series has several self-protective functions, such as Overload Protection (OLP), Abnormal Over-Current protection (AOCP), Over-Voltage Protection (OVP), and Thermal Shutdown (TSD). All the protections are implemented as autorestart mode. Once the fault condition is detected, switching is terminated and the SenseFET remains off. This causes  $V_{CC}$  to fall. When  $V_{CC}$  falls down to the Under-Voltage Lockout (UVLO) stop voltage of 8V, the protection is reset and start-up circuit charges V<sub>CC</sub> capacitor. When the V<sub>CC</sub> reaches the start voltage of 12V. the FSQ-series resumes normal operation. If the fault condition is not removed, the SenseFET remains off and V<sub>CC</sub> drops to stop voltage again. In this manner, the auto-restart can alternately enable and disable the switching of the power SenseFET until the fault condition is eliminated. Because these protection circuits are fully integrated into the IC without external components, the reliability is improved without increasing cost.

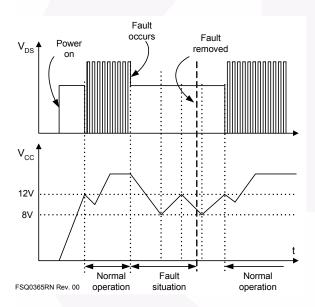


Figure 23. Auto Restart Protection Waveforms

4.1 Overload Protection (OLP): Overload is defined as the load current exceeding its normal level due to an unexpected abnormal event. In this situation, the protection circuit should trigger to protect the SMPS. However, even when the SMPS is in the normal operation, the overload protection circuit can be triggered during the load transition. To avoid this undesired operation, the overload protection circuit is designed to trigger only after a specified time to determine whether it is a transient situation or a true overload situation. Because of the pulse-by-pulse current limit capability, the maximum peak current through the Sense FET is limited, and therefore the maximum input power is restricted with a given input

voltage. If the output consumes more than this maximum power, the output voltage ( $V_{O}$ ) decreases below the set voltage. This reduces the current through the optocoupler LED, which also reduces the opto-coupler transistor current, thus increasing the feedback voltage ( $V_{FB}$ ). If  $V_{FB}$  exceeds 2.8V, D1 is blocked and the  $5\mu A$  current source starts to charge CB slowly up to  $V_{CC}$ . In this condition,  $V_{FB}$  continues increasing until it reaches 6V, when the switching operation is terminated, as shown in Figure 24. The delay time for shutdown is the time required to charge CB from 2.8V to 6V with  $5\mu A$ . A  $20\sim50 ms$  delay time is typical for most applications.

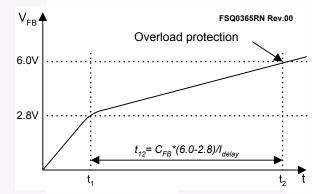


Figure 24. Overload Protection

4.2 Abnormal Over-Current Protection (AOCP): When the secondary rectifier diodes or the transformer pins are shorted, a steep current with extremely high-di/dt can flow through the SenseFET during the LEB time. Even though the FSQ-series has OLP (Overload Protection), it is not enough to protect the FSQ-series in that abnormal case, since severe current stress is imposed on the SenseFET until OLP triggers. The FSQ-series has an internal AOCP (Abnormal Over-Current Protection) circuit as shown in Figure 25. When the gate turn-on signal is applied to the power SenseFET, the AOCP block is enabled and monitors the current through the sensing resistor. The voltage across the resistor is compared with a preset AOCP level. If the sensing resistor voltage is greater than the AOCP level, the set signal is applied to the latch, resulting in the shutdown of the SMPS.

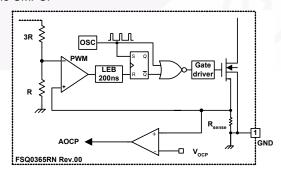


Figure 25. Abnormal Over-Current Protection

- 4.3 Over-Voltage Protection (OVP): If the secondary side feedback circuit malfunctions or a solder defect causes an opening in the feedback path, the current through the opto-coupler transistor becomes almost zero. Then, V<sub>FB</sub> climbs up in a similar manner to the overload situation, forcing the preset maximum current to be supplied to the SMPS until the overload protection triggers. Because more energy than required is provided to the output, the output voltage may exceed the rated voltage before the overload protection triggers, resulting in the breakdown of the devices in the secondary side. To prevent this situation, an OVP circuit is employed. In general, the peak voltage of the sync signal is proportional to the output voltage and the FSQ-series uses a sync signal instead of directly monitoring the output voltage. If the sync signal exceeds 6V, an OVP is triggered, shutting down the SMPS. To avoid undesired triggering of OVP during normal operation, the peak voltage of the sync signal should be designed below 6V.
- **4.4 Thermal Shutdown (TSD):** The SenseFET and the control IC are built in one package. This makes it easy for the control IC to detect the abnormal over temperature of the SenseFET. If the temperature exceeds ~150°C, the thermal shutdown triggers.
- **5. Soft-Start:** The FPS has an internal soft-start circuit that increases PWM comparator inverting input voltage with the SenseFET current slowly after it starts up. The typical soft-start time is 15ms, The pulse width to the power switching device is progressively increased to establish the correct working conditions for transformers, inductors, and capacitors. The voltage on the output capacitors is progressively increased with the intention of smoothly establishing the required output voltage. This mode helps prevent transformer saturation and reduces stress on the secondary diode during startup.
- **6. Burst Operation:** To minimize power dissipation in standby mode, the FPS enters burst-mode operation. As the load decreases, the feedback voltage decreases. As shown in Figure 26, the device automatically enters burst-mode when the feedback voltage drops below  $V_{BURL}$  (350mV). At this point, switching stops and the output voltages start to drop at a rate dependent on standby current load. This causes the feedback voltage to rise. Once it passes  $V_{BURH}$  (550mV), switching resumes. The feedback voltage then falls and the process repeats. Burst-mode operation alternately enables and disables switching of the power SenseFET, thereby reducing switching loss in standby mode.

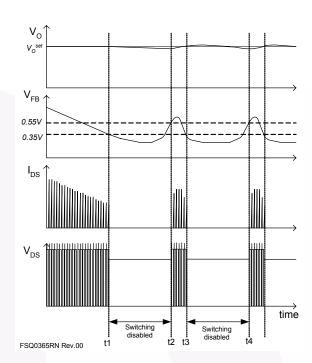


Figure 26. Waveforms of Burst Operation

7. Switching Frequency Limit: To minimize switching loss and EMI (Electromagnetic Interference), the MOSFET turns on when the drain voltage reaches its minimum value in valley switching operation. However, this causes switching frequency to increases at light load conditions. As the load decreases, the peak drain current diminishes and the switching frequency increases. This results in severe switching losses at light-load condition, as well as intermittent switching and audible noise. Because of these problems, the valley switching converter topology has limitations in a wide range of applications.

To overcome this problem, FSQ-series employs a frequency-limit function, as shown in Figures 27 and 28. Once the SenseFET is turned on, the next turn-on is prohibited during the blanking time (t<sub>B</sub>). After the blanking time, the controller finds the valley within the detection time window (t<sub>W</sub>) and turns on the MOSFET, as shown in Figures 27 and 28 (Cases A, B, and C). If no valley is found during t<sub>W</sub>, the internal SenseFET is forced to turn on at the end of t<sub>W</sub> (Case D). Therefore, our devices have a minimum switching frequency of 55kHz and a maximum switching frequency of 67kHz, as shown in Figure 28.

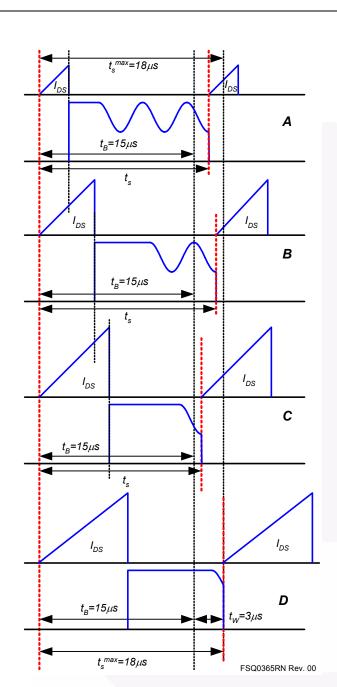


Figure 27. Valley Switching with Limited Frequency

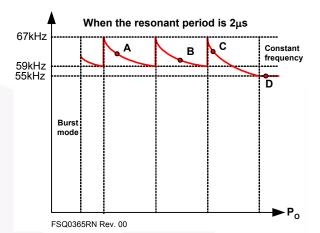


Figure 28. Switching Frequency Range

### Typical Application Circuit of FSQ0365RN

Application	FPS Device	Input Voltage Range	Rated Output Power	Output Voltage (Max. Current)
DVD Player Power Supply	FSQ0365RN	85-265V <sub>AC</sub>	19W	5.1V (1.0A) 3.4V (1.0A) 12V (0.4A) 16V (0.3A)

#### **Features**

- High efficiency ( >77% at universal input)
- Low standby mode power consumption (<1W at 230V<sub>AC</sub> input and 0.5W load)
- Reduce EMI noise through Valley Switching operation
- Enhanced system reliability through various protection functions
- Internal soft-start (15ms)

### **Key Design Notes**

- The delay time for overload protection is designed to be about 30ms with C107 of 47nF. If faster/slower triggering of OLP is required, C107 can be changed to a smaller/larger value (eg. 100nF for 60ms).
- The input voltage of V<sub>sync</sub> must be higher than -0.3V. By proper voltage sharing by R106 & R107 resistors, the input voltage can be adjusted.
- The SMD-type 100nF capacitor must be placed as close as possible to V<sub>CC</sub> pin to avoid malfunction by abrupt pulsating noises and to improved surge immunity.

#### 1. Schematic

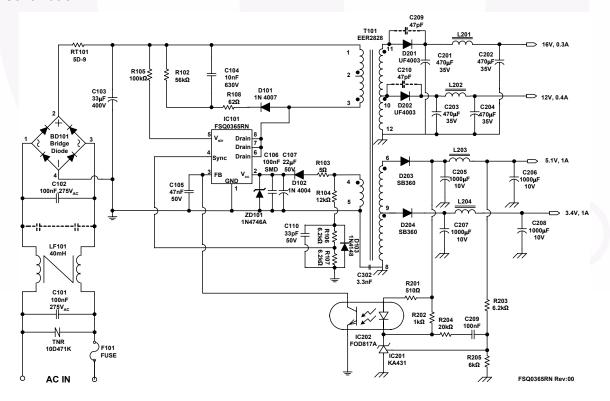


Figure 29. Demo Circuit of FSQ0365RN

#### 2. Transformer

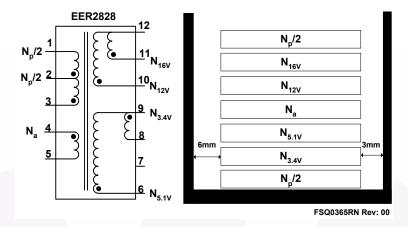


Figure 30. Transformer Schematic Diagram of FSQ0365RN

### 3. Winding Specification

No	Pin (s→f)	Wire	Turns	Winding Method					
N <sub>p</sub> /2	3 → 2	$0.25^{\phi} \times 1$	50	Center Solenoid Winding					
Insulation:	Polyester Tape t = 0.050	mm, 2 Layers							
N <sub>3.4V</sub>	9 → 8	$0.33^{\varphi}\times 2$	4	Center Solenoid Winding					
Insulation:	Insulation: Polyester Tape t = 0.050mm, 2 Layers								
N <sub>5V</sub>	6 → 9	$0.33^{\phi} \times 1$	2	Center Solenoid Winding					
Insulation:	Polyester Tape t = 0.050	mm, 2 Layers							
N <sub>a</sub>	4 → 5	$0.25^{\phi}  imes 1$	16	Center Solenoid Winding					
Insulation:	Polyester Tape t = 0.050	mm, 2 Layers							
N <sub>12V</sub>	10 → 12	$0.33^{\varphi}\times3$	14	Center Solenoid Winding					
Insulation:	Polyester Tape t = 0.050	mm, 3 Layers							
N <sub>16V</sub>	11 → 12	$0.33^{\varphi}\times3$	18	Center Solenoid Winding					
Insulation: Polyester Tape t = 0.050mm, 2 Layers									
N <sub>p</sub> /2	2 → 1	$0.25^{\phi} \times 1$	50	Center Solenoid Winding					
Insulation: Polyester Tape t = 0.050mm, 2 Layers									

#### 4. Electrical Characteristics

	Pin	Specification	Remarks
Inductance	1 - 3	1.4mH ± 10%	100kHz, 1V
Leakage	1 - 3	25μH Max.	Short all other pins

#### 5. Core & Bobbin

■ Core: EER2828 (Ae=86.66mm<sup>2</sup>)

■ Bobbin: EER2828

#### 6. Demo Board Part List

Part	Value	e Note		Value	Note	
	Resis	stor	Inductor			
R102	56kΩ	1W	L201	10μH		
R103	5Ω	1/2W	L202	10μH		
R104	12kΩ	1/4W	L203	4.9µH		
R105	100kΩ	1/4W	L204	4.9µH		
R106	6.2kΩ	1/4W		Diod	е	
R107	6.2kΩ	1/4W	D101	IN4007		
R108	62Ω	1W	D102	IN4004		
R201	510Ω	1/4W	ZD101	1N4746A		
R202	1kΩ	1/4W	D103	1N4148		
R203	6.2kΩ	1/4W	D201	UF4003		
R204	20kΩ	1/4W	D202	UF4003		
R205	6kΩ	1/4W	D203	SB360		
	Capa	citor	D204	\$ SB360		
C101	100nF/275V <sub>AC</sub>	Box Capacitor				
C102	100nF/275V <sub>AC</sub>	Box Capacitor		IC		
C103	33µF/400V	Electrolytic Capacitor	IC101	FSQ0365RN	FPS™	
C104	10nF/630V	Film Capacitor	IC201	KA431 (TL431)	Voltage reference	
C105	47nF/50V	Mono Capacitor	IC202	FOD817A	Opto-coupler	
C106	100nF/50V	SMD (1206)		Fuse	е	
C107	22μF/50V	Electrolytic Capacitor	Fuse	2A/250V		
C110	33pF/50V	Ceramic Capacitor		NTC		
C201	470μF/35V	Electrolytic Capacitor	RT101	5D-9		
C202	470µF/35V	Electrolytic Capacitor		Bridge D	Diode	
C203	470µF/35V	Electrolytic Capacitor	BD101	2KBP06M2N257	Bridge Diode	
C204	470μF/35V	Electrolytic Capacitor	Line Filter		lter	
C205	1000μF/10V	Electrolytic Capacitor	LF101 40mH			
C206	1000μF/10V	Electrolytic Capacitor		Transfo	rmer	
C207	1000μF/10V	Electrolytic Capacitor	T101			
C208	1000μF/10V	Electrolytic Capacitor		Varist	tor	
C209	100nF /50V	Ceramic Capacitor	TNR	10D471K		

### Typical Application Circuit of FSQ311

Application	FPS Device	Input Voltage Range	Rated Output Power	Output Voltage (Max. Current)
DVD Player Power Supply	FSQ311	85-265V <sub>AC</sub>	8W	5.1V (0.9A) 3.3V (0.9A) 12V (0.03A) 16V (0.03A)

#### **Features**

- High efficiency ( >70% at universal input)
- Low standby mode power consumption (<1W at 230V<sub>AC</sub> input and 0.5W load)
- Reduce EMI noise through Valley Switching operation
- Enhanced system reliability through various protection functions
- Internal soft-start (15ms)

### **Key Design Notes**

- The delay time for overload protection is designed to be about 30ms with C107 of 47nF. If faster/slower triggering of OLP is required, C107 can be changed to a smaller/larger value (eg. 100nF for 60ms).
- The input voltage of V<sub>sync</sub> must be higher than -0.3V. By proper voltage sharing by R106 & R107 resistors, the input voltage can be adjusted.
- The SMD-type 100nF capacitor must be placed as close as possible to V<sub>CC</sub> pin to avoid malfunction by abrupt pulsating noises and to improved surge immunity.

#### 1. Schematic

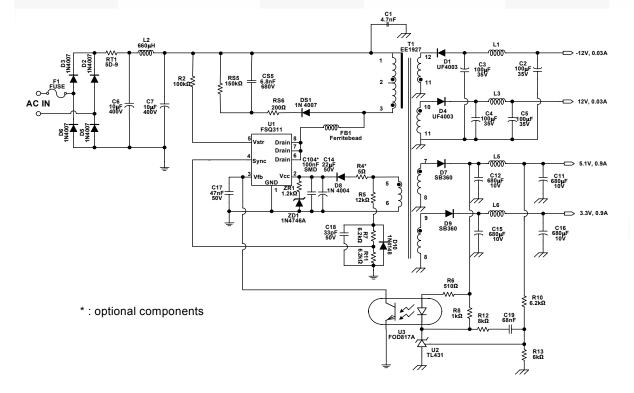


Figure 31. Demo Circuit of FSQ311

#### 2. Transformer

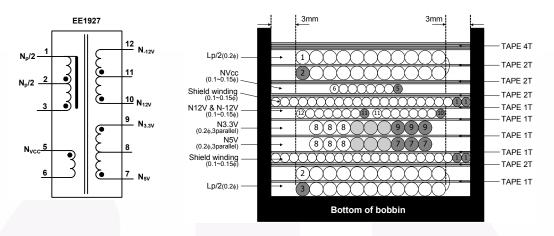


Figure 32. Transformer Schematic Diagram of FSQ311

### 3. Winding Specification

No	Pin (s→f)	Wire	Turns	Winding Method	
N <sub>p</sub> /2	3 → 2	$0.2^{\phi} \times 1$	111	Solenoid Winding, 2 Layers	
Insulation:	Polyester Tape t = 0.025	imm, 2 Layers			
Shield	1 → open	$0.1^{\phi} \times 2$		Shield winding	
Insulation:	Polyester Tape t = 0.025	imm, 1 Layer			
N <sub>5V</sub>	7 → 8	$0.2^{\phi} \times 3$	15	Center Solenoid Winding	
Insulation: Polyester Tape t = 0.025mm, 1 Layer					
N <sub>3.3V</sub>	9 → 8	$0.2^{\phi} \times 3$	10	Center Solenoid Winding	
Insulation: Polyester Tape t = 0.025mm, 1 Layer					
N <sub>12V</sub>	10 → 11	0.1 <sup>∳</sup> × 1	30	Solenoid Winding	
N <sub>-12V</sub>	11 → 12	$0.1^{\phi} \times 3$	33	Solenoid Winding	
Insulation:	Polyester Tape t = 0.025	imm, 1 Layer			
Shield	1 → open	$0.1^{\phi} \times 2$		Shield winding	
Insulation:	Polyester Tape t = 0.025	imm, 2 Layers			
N <sub>VCCV</sub>	5 → 6	$0.1^{\phi} \times 1$	36	Center Solenoid Winding	
Insulation:	Polyester Tape t = 0.025	imm, 2 Layers			
N <sub>p</sub> /2	2 → 1	$0.2^{\phi} \times 1$	111	Solenoid Winding, 2 Layers	
Insulation:	Polyester Tape t = 0.025	imm, 4 Layers			

#### 4. Electrical Characteristics

	Pin	Specification	Remarks
Inductance	1 - 3	2.1mH ± 10%	66kHz, 1V
Leakage	1 - 3	100μH Max.	Short all other pins

#### 5. Core & Bobbin

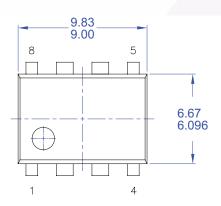
■ Core: EE1927 (Ae=23.4mm<sup>2</sup>)

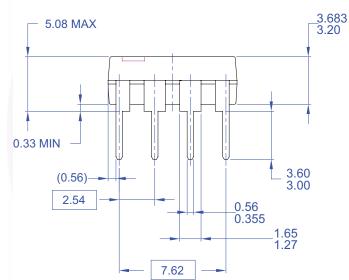
■ Bobbin: EE1927

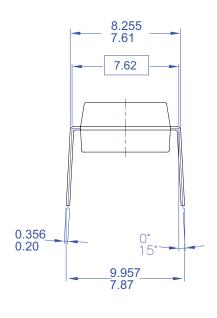
#### 6. Demo Board Part List

Part	Value	Note	Part	Value	Note	
Resistor				Inductor		
R2	100kΩ	1/4W	L2	660µH		
ZR1	1.2kΩ	1/4W	L1	4.7µH		
R4	5Ω	1/2W	L3	4.7µH		
R5	12kΩ	1/4W	L5	4.7µH		
R7	6.2kΩ	1/4W	L6	4.7µH		
R11	6.2kΩ	1/4W		Diode		
RS5	150kΩ	2W	D2,3,4,5	IN4007		
RS6	200Ω	1W	D8	IN4004		
R6	510Ω	1/4W	D10	1N4148		
R8	1kΩ	1/4W	ZD1	1N4746A		
R12	8kΩ	1/4W	DS1	1N4007		
R10	6.2kΩ	1/4W, 1%	D1	UF4003		
R13	6kΩ	1/4W, 1%	D4	UF4003		
	Сарас	citor	D7	SB360		
C6	10μF/400V	Electrolytic	D9	SB360		
C7	10μF/400V	Electrolytic		IC		
C17	47nF/50V	Ceramic	U1	FSQ311	FPS™	
C104	100nF/50V	SMD(1206)	U2	KA431 (TL431)	Voltage reference	
C14	22μF/50V	Electrolytic	U3	FOD817A	Opto-coupler	
C18	33pF/50V	Ceramic		Fuse		
CS5	6.8nF/680V	Film	Fuse	2A/250V		
C2	100μF/35V	Electrolytic		NTC		
C3	100μF/35V	Electrolytic	RT1	RT1 5D-9		
C4	100μF/35V	Electrolytic		Transformer		
C5	100μF/35V	Electrolytic	T1	EE1927	Bridge Diode	
C11	680μF/10V	Electrolytic		Ferrite bead		
C12	680μF/10V	Electrolytic	FB1			
C15	680μF/10V	Electrolytic				
C16	680μF/10V	Electrolytic				
C19	68nµF/50V	Ceramic			T IRI	
C1	4.7nF/375V <sub>AC</sub>	Ceramic				

### **Package Dimensions**





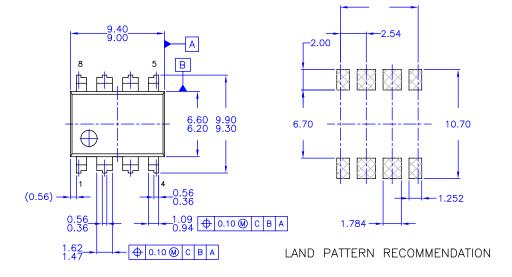


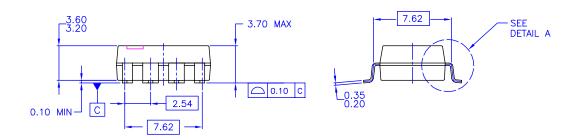
NOTES: UNLESS OTHERWISE SPECIFIED

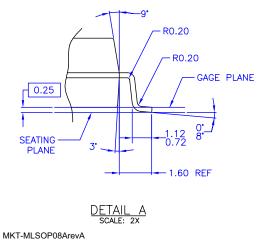
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- D) DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994
- E) DRAWING FILENAME AND REVSION: MKT-N08FREV2.

Figure 33. 8-Lead, Dual In-Line Package(DIP)

### Package Dimensions (Continued)







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  B) ALL DIMENSIONS ARE IN MILLIMETERS.

  C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994

Figure 34. 8-Lead, LSOP Package





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